

WAFER PROCESSING METHOD AND MACHINE

ABSTRACT OF THE DISCLOSURE

In a processing method for a wafer with a mark formed in an outer peripheral portion thereof, a frame unit having the wafer, a tape, and a ring frame is provided, a set of processing conditions for processing the wafer is selected, and a representative image associated with the set of processing conditions is displayed on a display unit. The ring frame includes a notch formed in an outer periphery thereof. In the frame unit, the mark and the notch are in a positional relationship set in accordance with the set of processing conditions. The positional relationship is presented in the representative image.

[Fig. 3A]